SMT power inductors

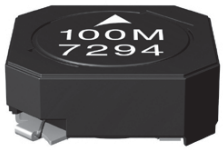
Size 6.3 × 6.3 × 2.5 (mm)

Series/Type: **B82462G2**

Date: June 2012

SMD

Rated inductance 0.82 ... 330 µH
Rated current 0.22 ... 3.25 A



Construction

- Ferrite core
- Magnetically shielded
- Winding: enamel copper wire
- Winding welded to terminals

Features

- Temperature range up to +150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- Qualified to AEC-Q200
- RoHS-compatible

Applications

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Industrial electronics

Terminals

- Base material CuSn6
- Layer composition Ag, Sn (lead-free)[1)]
- Electro-plated

Marking

- Marking on component:
  Manufacturer, L value (nH, coded),
  L tolerance (coded), manufacturing date (YWWD)
- Minimum data on reel:
  Manufacturer, ordering code, L value,
  quantity, date of packing

Delivery mode and packing unit

- 12-mm blister tape, wound on 330-mm ∅ reel
- Packing unit: 2500 pcs./reel

1) Ni-barrier-plated terminals on request (B82462G2*50).

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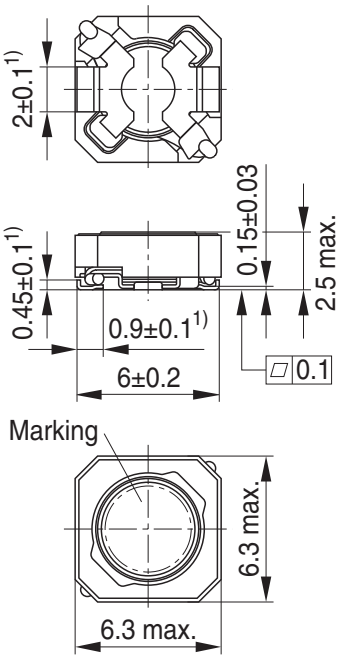
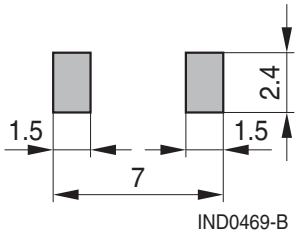
Dimensional drawing and layout recommendation





IND0469-B

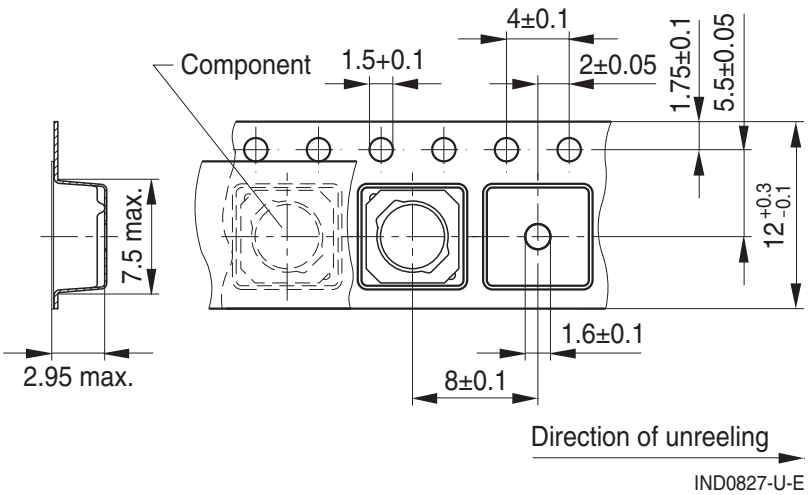
Dimensions in mm

1) Soldering area

IND0470-D-E

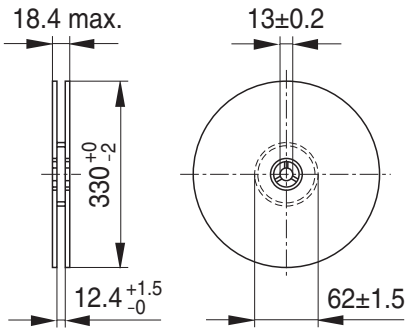
Taping and packing

Blister tape



IND0827-U-E

Reel



IND0350-S

Dimensions in mm

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Technical data and measuring conditions

Rated inductance L_R	Measured with impedance analyzer Agilent 4294A at frequency f_L, 0.1 V, +20 °C
Rated temperature T_R	+85 °C
Rated current I_R	Max. permissible DC with temperature increase of ≤ 40 K at rated temperature
Saturation current I_{sat}	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%
DC resistance R_{max}	Measured at +20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (5 ±0.3) s Wetting of soldering area ≥ 90% (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s as referenced in JEDEC J-STD 020D
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: –55 °C … +150 °C Packaged: –25 °C … +40 °C, ≤ 75% RH
Weight	Approx. 1.5 g

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Characteristics and ordering codes

L_R µH	Tolerance	f_L MHz	I_R A	I_{sat} A	R_{max} Ω	Ordering code
0.82	±20% ≙ M	0.1	3.25	4.40	0.017	B82462G2821M000
1.0		0.1	3.25	4.25	0.017	B82462G2102M000
1.2		0.1	3.10	3.60	0.019	B82462G2122M000
1.8		0.1	2.75	3.00	0.022	B82462G2182M000
2.2		0.1	2.30	2.55	0.032	B82462G2222M000
3.3		0.1	2.00	2.05	0.040	B82462G2332M000
4.7		0.1	1.60	1.80	0.061	B82462G2472M000
6.8		0.1	1.45	1.48	0.078	B82462G2682M000
10		0.1	1.25	1.28	0.106	B82462G2103M000
15		0.1	1.02	1.02	0.160	B82462G2153M000
22		0.1	0.83	0.83	0.245	B82462G2223M000
33		0.1	0.68	0.68	0.345	B82462G2333M000
47		0.1	0.62	0.56	0.420	B82462G2473M000
68		0.1	0.48	0.47	0.635	B82462G2683M000
100		0.1	0.41	0.41	0.950	B82462G2104M000
150		0.1	0.33	0.31	1.480	B82462G2154M000
220		0.1	0.28	0.26	2.10	B82462G2224M000
330		0.1	0.22	0.20	3.25	B82462G2334M000

1) For Ni-barrier-plated terminals replace the last two digits “00” by “50”.

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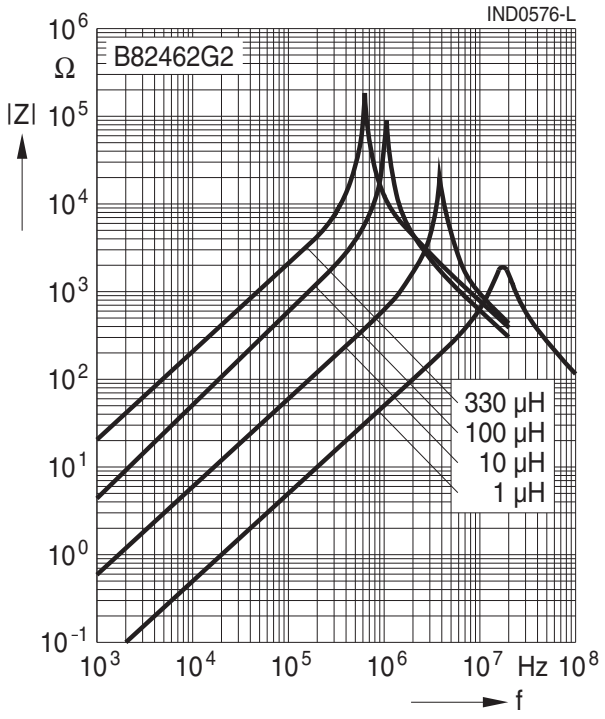
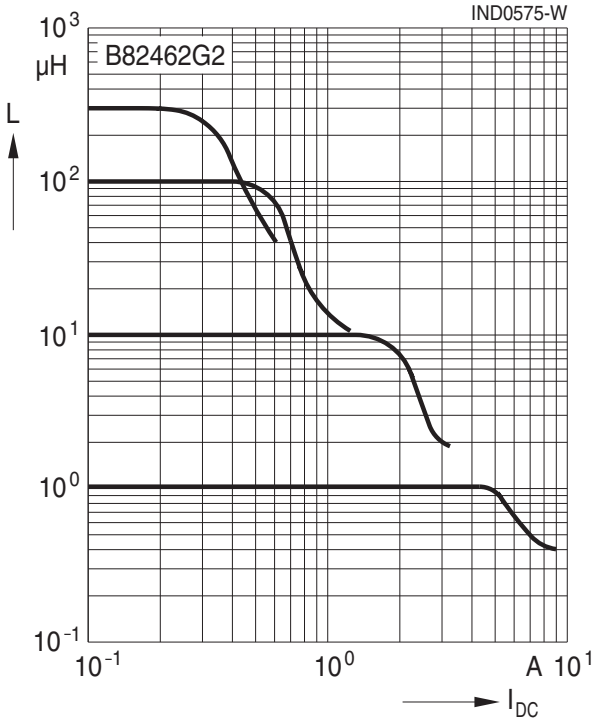
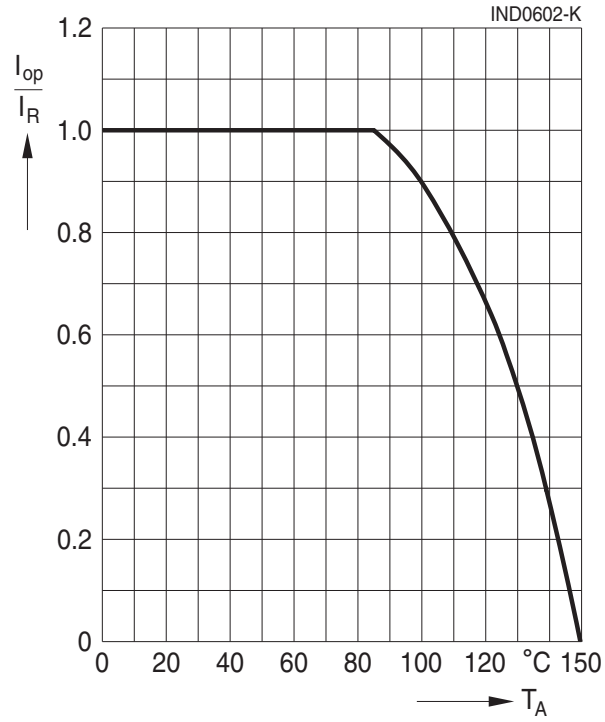
Impedance |Z| versus frequency f
measured with impedance analyzer Agilent 4294A, typical values at +20 °C



Inductance L versus DC load current I_{DC}
measured with LCR meter Agilent 4275A, typical values at +20 °C



Current derating I_{op}/I_R versus ambient temperature T_A
(rated temperature T_R = +85 °C)



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
  Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

Important notes

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